

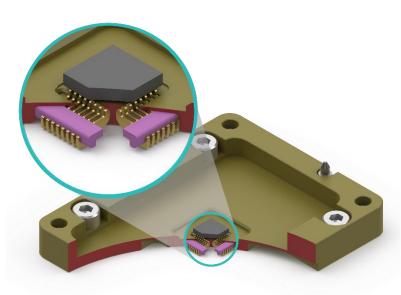
EZ CONTACT™

TEST CONTACTING SOLUTION (PATENT NO. US 10,578,645)

FOR ANALOG / RF / MMWAVE DEVICE TESTING

EZ Contact High Performance Test Contacting Solution designed and validated for initial lab characterization through high-volume production test environments. EZ Contact technology is a proprietary short rigid contacting solution with a single multifunctional elastomer for biasing and controlling contact motion. It encompasses the patented technology of SWS (Short Wiping Stroke) along with ACF (Advanced Contact Finishing), and TCC (Thermal Conditioning Channel) Technology to meet your most demanding High Performance Electrical and Mechanical Test Requirements. Product is easily integrated into most IC Handler platforms.

Key Features	EZ Contact Technology Delivers	
Single Multifunctional Elastomer	Easy Installation, Inventory and Cost Reduction, Consistent / Controlled Contact Motion, Consistent CRes, Longer MTBA	
Short Electrical Length	Superior Signal Performance	
No Contact Pin Engagement with Back Wall of Socket Housing	No Wearing of the Socket Housing, Extended Lifespan	
SWS (Short Wiping Stroke) Technology	Ideal for Short Pads, Chamfered Corner Pads, Wettable Flank, and Step Cut Styles	
ACF (Advanced Contact Finishing) Technology	Loadboard Friendly, Minimizes Debris, Prolonged Cleaning	
TCC (Thermal Conditioning Channel) Technology	Excellent thermal stability	

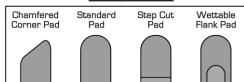


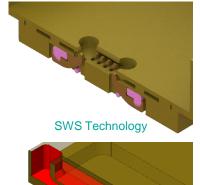
Package Range: QFN, DFN, LGA, QFP, TSOP, SOIC, SOP

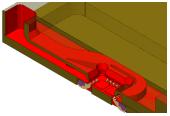
Pitch : ≥ 0.3mm

Available in Non-Kelvin Configurations ONLY

Designed For







TCC Technology – Excellent thermal stability

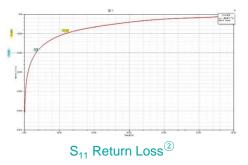
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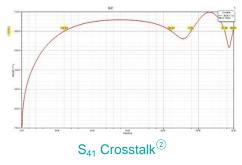
Electrical Specifications	EZ – 1 *	EZ – 2 * ^①
Self Inductance (nH)	0.35	0.76
Mutual Inductance (nH)	0.15	0.46
Ground Capacitance (pF)	0.07	0.15
Mutual Capacitance (pF)	0.04	0.11
S21 (Insertion Loss / Bandwidth)	- 1dB @ 36GHz	- 1dB @ 18GHz
S11 (Return Loss / Bandwidth)	- 20dB @ 15GHz	- 20dB @ 3GHz
S41 (Crosstalk / Bandwidth)	- 20dB @ 13GHz	- 20dB @ 12GHz
Contact DC Resistance (mΩ)	≤ 25	≤ 25
Current Carrying Capacity (A) Duty Cycle 100%	N/A	9
Current Leakage (pA) @ 10V	≤ 1	≤ 1

Current Leakage (pA) @ 10V	≤ 1	≤ 1	
Mechanical Specifications	EZ - 1	EZ - 2	
Contact Uncompressed (mm)	0.93	1.6	
Contact Compliance (mm)	0.18	0.2	
Contact Tip Coplanarity (mm)	± 0.05 *	± 0.05 *	
Contact Wiping Length (mm)	~ 0.1 *	~ 0.1 *	
Gram Force per Contact (g)	25 ~ 35 *	30 ~ 40 *	
Number of Insertions – Housing	≥ 6M *	≥ 6M *	
Number of Insertions - Elastomer	~ 200k *	~ 300k *	
Number of Insertions – Pin (Matte Tin)	2001. 2001. *	2001, 5001, *	
Number of Insertions – Pin (NiPd)	200k ~ 300k *	300k ~ 500k *	
Operating Temperature (°C)	- 45 ~ 155	- 45 ~ 155	
Socket Material	Torlon® 5030 or equivalent	Torlon® 5030 or equivalent	
Contact Pin Material	BeCu - NiAu	BeCu - NiAu	

EZ-2 Performance







Grounding Options

Bell Contact (BC)	Hinged Contact Insert (HCI)	EZ Contact	Ground Block with Contact(s)
≥ 2x2	≥ 3x3	≥ 5x5	≥ 2x2 (with BC) ≥ 3x3 (with HCI) ≥ 5x5 (with EZ)
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- Based on EZ-2 Contact with 0.50mm pitch
 Simulated Results

Note *: The stated specifications are based on JF Microtechnology's Laboratory Test; the results may vary subjected to the test environment conditions. Information furnished by JF Microtechnology is believed to be accurate and reliable. However, no responsibility is assumed by JF Microtechnology for its use, nor for any infringements of patents or other rights of third parties that may result from its use. Specifications subject to change without notice. No license is granted by implication or otherwise under any patent or patent rights of JF Microtechnology. Trademarks and registered trademarks are the property of their respective owners.

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